BYV26AGP THRU BYV26EGP

SINTERED GLASS JUNCTION **FAST SWITCHING PLASTIC RECTIFIER**

VOLTAGE: 200V to 1000V **CURRENT: 1.0A**



FEATURE

High temperature metallurgically bonded construction Sintered glass cavity free junction Capability of meeting environmental standard of

MIL-S-19500

High temperature soldering guaranteed 350°C /10sec/0.375"lead length at 5 lbs tension Operate at Ta =55°C with no thermal run away

Typical Ir<0.1µA

MECHANICAL DATA

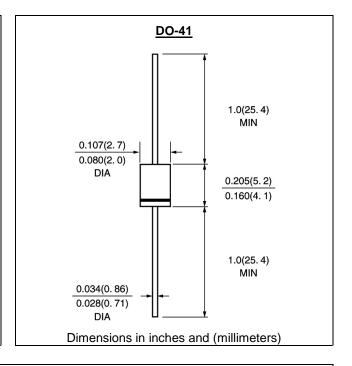
Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C

Case: Molded with UL-94 Class V-0 recognized Flame

Retardant Epoxy

Polarity: color band denotes cathode

Mounting position: any



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

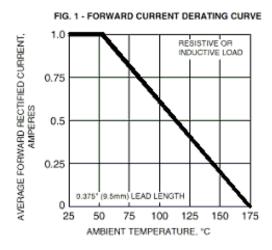
	SYMBOL	BYV26 AGP	BYV26 BGP	BYV26 CGP	BYV26 DGP	BYV26 EGP	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	200	400	600	800	1000	V
Maximum RMS Voltage	Vrms	140	280	420	560	700	V
Maximum DC blocking Voltage	Vdc	200	400	600	800	1000	V
Reverse avalanche breakdown voltage at IR = 0.1 mA	V(BR)R (min)	300	500	700	900	1100	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =55°C	If(av)	1.0					А
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	Ifsm	30					А
Maximum Forward Voltage at rated Forward Current and 50°C	Vf	2.5					V
Non-repetitive peak reverse avalanche energy (Note 1)	Ersm	10					mJ
Maximum DC Reverse Current Ta =25°C	lr 5.0				μΑ		
at rated DC blocking voltage Ta =150°C	150.0					μΑ	
Maximum Reverse Recovery Time (Note 2)	Trr	30 75			75	nS	
Typical Junction Capacitance (Note 3)	Cj	15.0					pF
Typical Thermal Resistance (Note 4)	R θ ja	55.0					°C /W
Storage and Operating Junction Temperature	Tstg, Tj	-65 to +175					°C

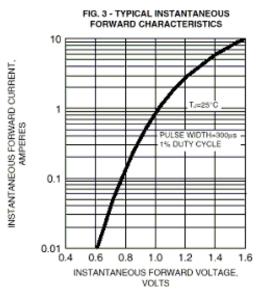
Note: 1.R=400mA; Tj=Tjmax prior to surge; inductive load switched off

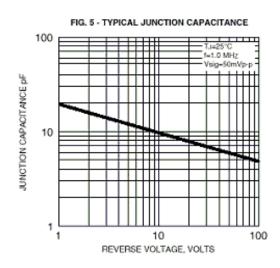
- 2.Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
- 3. Measured at 1.0 MHz and applied reverse voltage of 4.0 Vdc
- 4. Thermal Resistance from Junction to Ambient at 3/8"lead length, P.C. Board Mounted

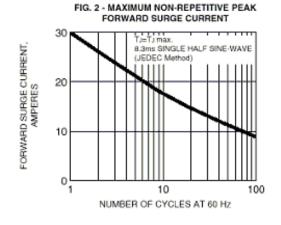
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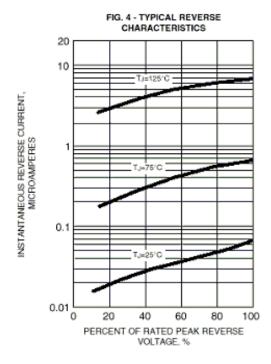
RATINGS AND CHARACTERISTIC CURVES BYV26AGP THRU BYV26EGP

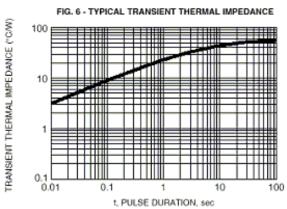












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